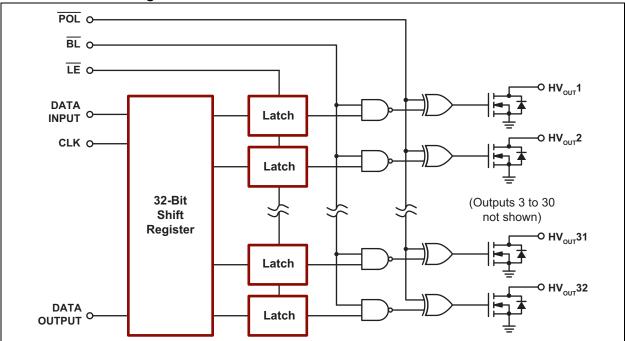
Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Supply Voltage, V _{DD} (Note 1)	–0.5V to +7V
Logic Input Levels (Note 1)	
Ground Current (Note 2)	1.5A
Storage Temperature, T _S	65°C to +150°C
44-lead QFN (Note 3)	3.4W
Output Voltage, HV _{OUT} (Note 1) Logic Input Levels (Note 1) Ground Current (Note 2) Maximum Junction Temperature, T _{J(MAX)} Storage Temperature, T _S Continuous Total Power Dissipation:	

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

- Note 1: All voltages are referenced to V_{SS}.
 - 2: Duty cycle is limited by the total power dissipated in the package.
 - 3: 1 oz. 4-layer 3" x 4" PCB

RECOMMENDED OPERATING CONDITIONS

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Logic Supply Voltage	V_{DD}	4.5	_	5.5	V	
High-Voltage Output	HV _{OUT}	-0.3	_	+220	V	
High-Level Input Voltage	V _{IH}	0.8 V _{DD}	_	V_{DD}	V	
Low-Level Input Voltage	V_{IL}	0	_	0.2 V _{DD}	V	
Clock Frequency	f _{CLK}	_	_	16	MHz	
Operating Ambient Temperature	T _A	-40	_	+85	°C	

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: Over recommended operating conditions unless otherwise noted.										
Paramete	Sym.	Min.	Тур.	Max.	Unit	Conditions				
V _{DD} Supply Current		I _{DD}	_	_	25	mA	f _{CLK} = 16 MHz, f _{DATA} = 8 MHz			
Quiescent V _{DD} Supply	I _{DDQ}	_	_	100	μA	D _{IN} = 0V, all input logic pins = 0V, all outputs off				
Off-State Output Current		I _{O(OFF)}	_		10	μA	All outputs high, all switches parallel			
High-Level Logic Input	t Current	I _{IH}	_	_	1	μA	$V_{IH} = V_{DD}$			
Low-Level Logic Input	Current	I _{IL}	_	_	-1	μA	V _{IL} = 0V			
High-Level Output Dat	ta Out	V _{OH}	V _{DD} -1V	_	_	V	ID _{OUT} = -10 mA			
Low-Level Output	ow-Level Output HV _{OUT}		_	_	15	V	IHV _{OUT} = +100 mA			
Voltage	Data Out	V _{OL}	_	_	1	V	ID _{OUT} = +10 mA			
HV _{OUT} Clamp Voltage	;	V _{oc}	_	_	-1.5	V	I _{OL} = -100 mA			

AC ELECTRICAL CHARACTERISTICS

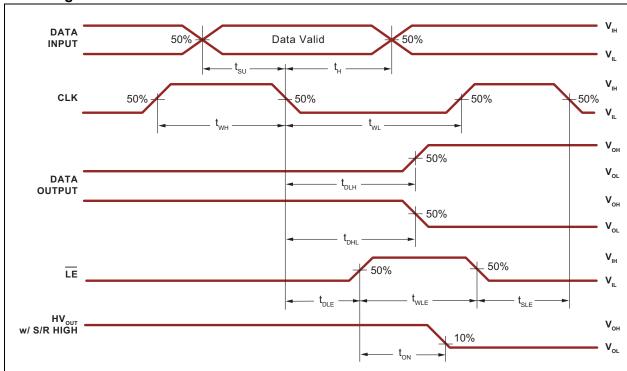
Electrical Specifications: $V_{DD} = 5V$, $T_J = 25$ °C										
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions				
Clock Frequency	f _{CLK}	_	_	16	MHz					
Clock Pulse Width, High or Low	t _{WL} , t _{WH}	31	_	_	ns					
Data Setup Time Before CLK Falls	t _{SU}	25	_	_	ns					
Data Hold Time after CLK Falls	t _H	10	_	_	ns					
Turn-On Time, HV _{OUT} from Enable	t _{ON}	_	_	400	ns	$R_L = 2 k\Omega$ to V_{PP} maximum				
Delay Time Clock to Data High to Low	t _{DHL}	_	_	35	ns	C _L = 15 pF				
Delay Time Clock to Data Low to High	t _{DLH}	_	_	35	ns	C _L = 15 pF				
Delay Time Clock to LE Low to High	t _{DLE}	20	_	_	ns					
Width of LE Pulse	t _{WLE}	20	_	_	ns					
LE Setup Time Before Clock Falls	t _{SLE}	20	_	_	ns					
Digital Logic Input Capacitance	C _{IN}	_	_	15	pF					

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions		
TEMPERATURE RANGE								
Operating Ambient Temperature	T_A	-40	_	+85	°C			
Maximum Junction Temperature	$T_{J(MAX)}$	_	_	+125	°C			
Storage Temperature	T _S	-65		+150	°C			
PACKAGE THERMAL RESISTANCE								
44-lead QFN	θ_{JA}	_	19	_	°C/W	Note 1		

Note 1: 1 oz. 4-layer 3" x 4" PCB

Switching Waveforms



2.0 PIN DESCRIPTION

The details on the pins of HV5523 are listed in Table 2-1. Refer to **Package Type** for the location of pins.

TABLE 2-1: 44-LEAD QFN PIN FUNCTION TABLE

Pin Number Pin	Name	Description
1 HV	_{OUT} 11	High-voltage output
2 HV	OUT12	High-voltage output
3 HV	OUT13	High-voltage output
4 HV	_{OUT} 14	High-voltage output
5 HV	_{OUT} 15	High-voltage output
6 HV	_{OUT} 16	High-voltage output
7 HV	_{OUT} 17	High-voltage output
8 HV	OUT ¹⁸	High-voltage output
9 HV	_{OUT} 19	High-voltage output
10 HV	OUT ²⁰	High-voltage output
11 HV	out21	High-voltage output
12 HV	OUT22	High-voltage output
13 HV	OUT23	High-voltage output
14 HV	OUT24	High-voltage output
15 HV	OUT ²⁵	High-voltage output
16 HV	OUT ²⁶	High-voltage output
17 HV	OUT27	High-voltage output
18 HV	OUT ²⁸	High-voltage output
19 HV	OUT ²⁹	High-voltage output
20 HV	OUT30	High-voltage output
21 HV	OUT31	High-voltage output
22 HV	OUT32	High-voltage output
23 DA1	ΓA OUT	Data output pin
24	NC	No internal connection
25	NC	No internal connection
26	NC	No internal connection
27 I	POL	Inverts the polarity of the HV _{OUT} pins
28	CLK	Clock pin. The Shift registers shift data on the falling edge of input clock.
29	VSS	Reference voltage, usually ground
30	/DD	Logic supply voltage
31	LE	Latch enable pin. Data is shifted from the Shift register to the latches on logic input high.
32 DA	ATA IN	Data input pin
33	BL	Blanking pin sets all HV _{OUT} pins ON or OFF, depending upon the state of polarity. See Table 3-2.
34	N/C	No internal connection

TABLE 2-1: 44-LEAD QFN PIN FUNCTION TABLE (CONTINUED)

Pin Number	Pin Name	Description
35	HV _{OUT} 1	High-voltage output
36	HV _{OUT} 2	High-voltage output
37	HV _{OUT} 3	High-voltage output
38	HV _{OUT} 4	High-voltage output
39	HV _{OUT} 5	High-voltage output
40	HV _{OUT} 6	High-voltage output
41	HV _{OUT} 7	High-voltage output
42	HV _{OUT} 8	High-voltage output
43	HV _{OUT} 9	High-voltage output
44	HV _{OUT} 10	High-voltage output
Cente	er Tab	Connect to VSS.

3.0 FUNCTIONAL DESCRIPTION

Follow the steps in Table 3-1 to power up and power down the HV5523.

TABLE 3-1: POWER-UP AND POWER-DOWN SEQUENCE

	Power-Up	Power-Down				
Step	Description	Step	Description			
1	Connect ground.	1	Remove all inputs.			
2	Apply V _{DD} .	2	Remove V _{DD} .			
3	Set all inputs to a known state.	3	Disconnect ground.			

TABLE 3-2: FUNCTION TABLE

			nputs ¹			Outputs						
Function		II	nputs			Sh	ift Register	High-V	oltage Output	Data Out		
	Data	CLK	LE	BL	POL	1	232	1	232			
All On	Х	Χ	Х	L	L	Note 2	Note 2	On	On	Note 2		
All Off	Х	Χ	Х	L	Н	Note 2	Note 2	Off	Off	Note 2		
Invert Mode	Х	Х	L	Н	L	Note 2	Note 2	Note 2	Note 2	Note 2		
Load S/R	H or L	↓	L	Н	Н	H or L	Note 2	Note 2	Note 2	Note 2		
	Х	H or L	1	Н	Н	Note 2	Note 2	Note 2	Note 2	Note 2		
Load Latches	Х	H or L	1	Н	L	Note 2	Note 2	Note 2	Note 2	Note 2		
Transparent	L	\downarrow	Н	Н	Н	L	Note 2	Off	Note 2	Note 2		
Latch Mode	Н	\downarrow	Н	Н	Н	Н	Note 2	On	Note 2	Note 2		

Note 1: H = High logic level

L = Low logic level

X = Don't care

↓ = Hight-to-low transition

↑ = Low-to-high transition

2: Dependent on previous stage's state before the last CLK \downarrow or last $\overline{\text{LE}}$ high

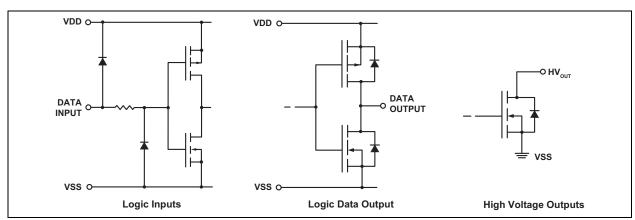


FIGURE 3-1: Input and Output Equivalent Circuits.

4.0 PACKAGE MARKING INFORMATION

4.1 Packaging Information

44-lead QFN

XXXXXXX @YYWWNNN Example

HV5523K7 @1912363

Legend: XX...X Product Code or Customer-specific information

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

e3 Pb-free JEDEC® designator for Matte Tin (Sn)

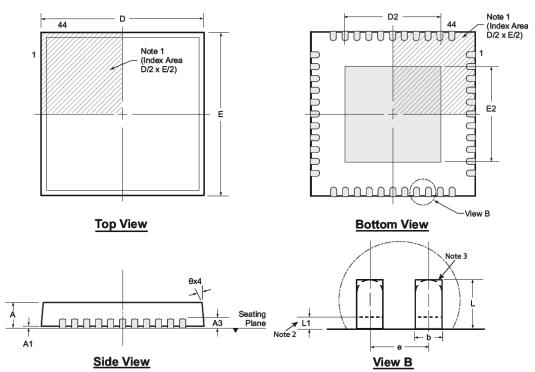
This package is Pb-free. The Pb-free JEDEC designator (e3)

can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

44-Lead QFN Package Outline (K7)

7.00x7.00mm body, 0.80mm height (max), 0.50mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

- A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
- a primed indicator.

 Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present.

 The inner tip of the lead may be either rounded or square.

Symb	ol	Α	A1	А3	b	D	D2	E	E 2	е	L	L1	θ
	MIN	0.70	0.00		0.18	6.85*	5.00 [†]	6.85*	5.00⁺		0.45†	0.00	0 º
Dimension (mm)	NOM	0.75	0.02	0.20 REF	0.25	7.00	5.15 [†]	7.00	5.15 [†]	0.50 BSC	0.55†	-	-
(/	MAX	0.80	0.05	-	0.30	7.15*	5.25 [†]	7.15*	5.25 [†]		0.65 [†]	0.15	14°

JEDEC Registration MO-220, Variation WKKD-3, Issue K, June 2006
* This dimension is not specified in the JEDEC drawing.

Drawings not to scale.

[†] This dimension differs from the JEDEC drawing.

APPENDIX A: REVISION HISTORY

Revision A (July 2019)

- Converted Supertex Doc# DSFP-HV5523 to Microchip DS20005700A
- Changed the quantity of the 44-lead QFN K7 package from 280/Tray to 260/Tray
- Changed the quantity of the 44-lead QFN K7 M933 media type from 2000/Reel to 3000/Reel
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	<u>XX</u>	-	<u>x</u> - <u>x</u>	Examples:	
Device	Package Options		Environmental Media Type	a) HV5523K7-G:	32-Channel Serial-to-Parallel Converter with Open-Drain Outputs, 44-lead (7x7) WQFN, 260/Tray
Device:	HV5523	=	32-Channel Serial-to-Parallel Converter with Open-Drain Outputs	b) HV5523K7-G-M933	: 32-Channel Serial-to-Parallel Converter with Open-Drain Outputs, 44-lead (7x7) WQFN, 3000/Reel
Package:	K7	=	44-lead (7x7) WQFN		
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package		
Media Type:	(blank)	=	260/Tray for a K7 Package		
	M933	=	3000/Reel for a K7 Package		

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